

ABSTRACT OF THE DISCLOSURE

The method for manufacturing an electronic part includes a step of forming an opening hole onto an insulating member sandwiched between a conductor film and a lower conductor layer, from the conductor film, a step of making a surface of the lower conductor layer adhering the insulating member as bottom of the opening hole, and making a metal plating as a conductor portion grow in the opening hole from the lower conductor layer. In the method, after metal plating has reached the conductor film, the metal plating is grown on the conductor film and the conductor portion as electrode, to thereby form a thickness enough to form an upper conductive layer.